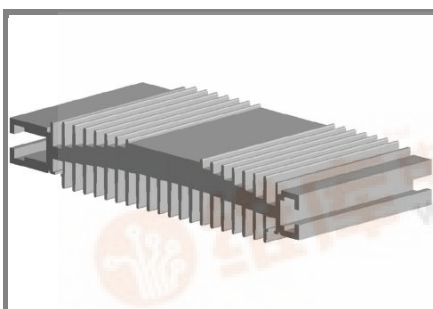


P 17



Heatsink

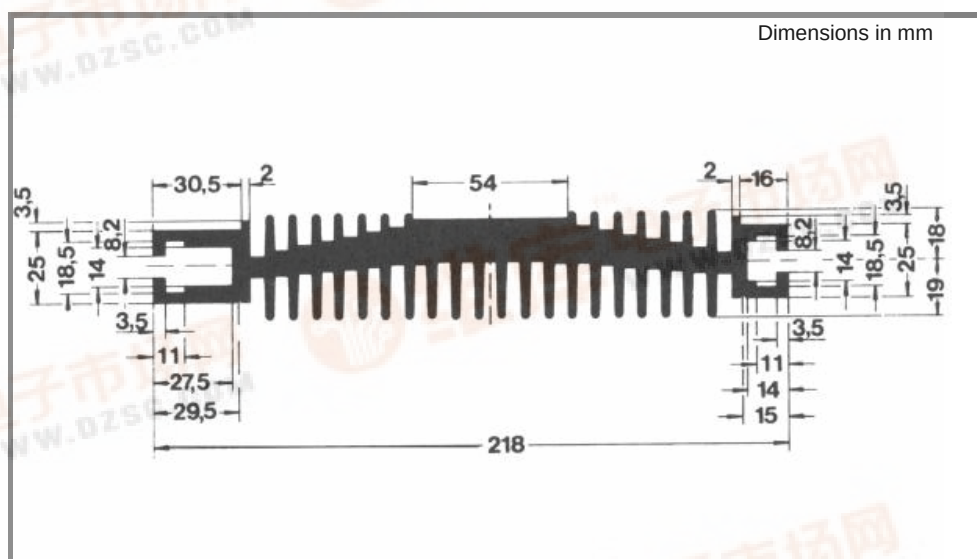
Standard lengths	n	b / d Ø mm	R _{thha} natural cooling K/W	R _{thca} (V _{air} /t) forced air cooling K/W	w kg
2x P 17/130		19 ± 1	0,49 (120W)	0,122 (300 m³/h)	3
		25 ± 2	0,48 (120W)	0,1 (300 m³/h)	
		33 ± 2	0,47 (120W)	0,085 (300 m³/h)	
P 17/130		19 ± 1		0,175 (300 m³/h)	2,9
+ 2x P 17/60		25 ± 2		0,14 (300 m³/h)	
STACK 1000		25 ± 2		0,135	38
(with P 17/130)		33 ± 2		0,122	
See Fig. Appl.2		47 ± 2		0,115	

For capsule devices

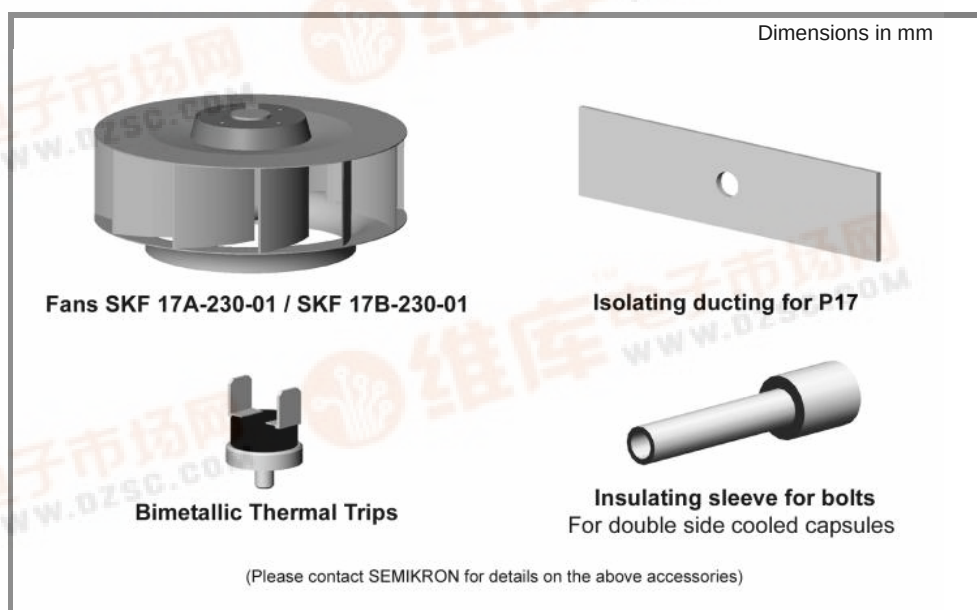
P 17

Features

- Intended for double-sided cooling of capsule devices with diameters upto 48mm
- Designed for forced air cooling
- Available as pre-assembled modules containing one or two capsules in a plastic frame
- Available in various lengths



P 17 general profile dimensions (w = 10,6 kg/m)



P 17 standard accessories

(Please contact SEMIKRON for details on the above accessories)

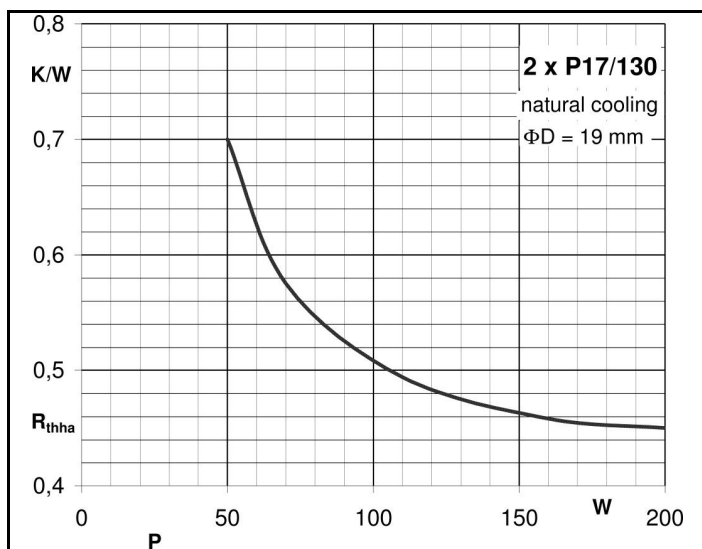


Fig.1 Thermal resistance vs. dissipated power

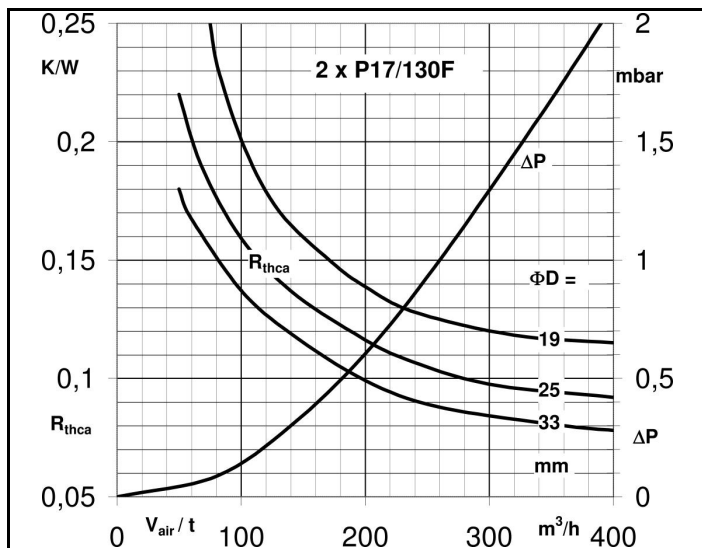


Fig.5a Thermal resistance and pressure drop vs. air flow

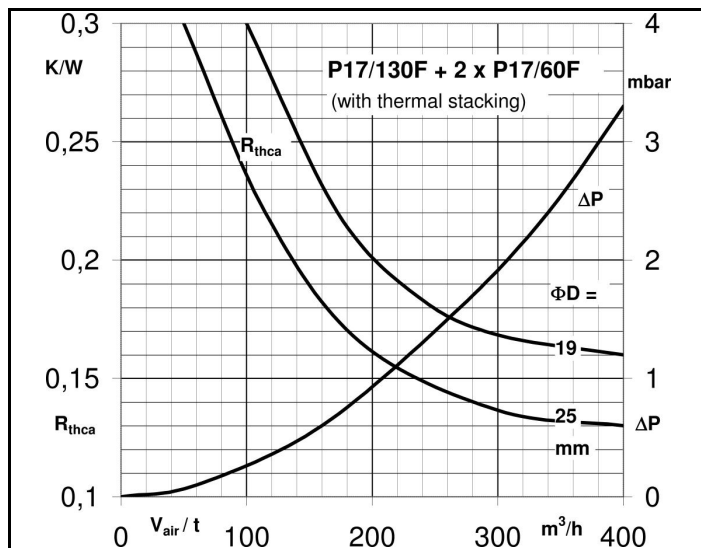


Fig.5b Thermal resistance and pressure drop vs. air flow

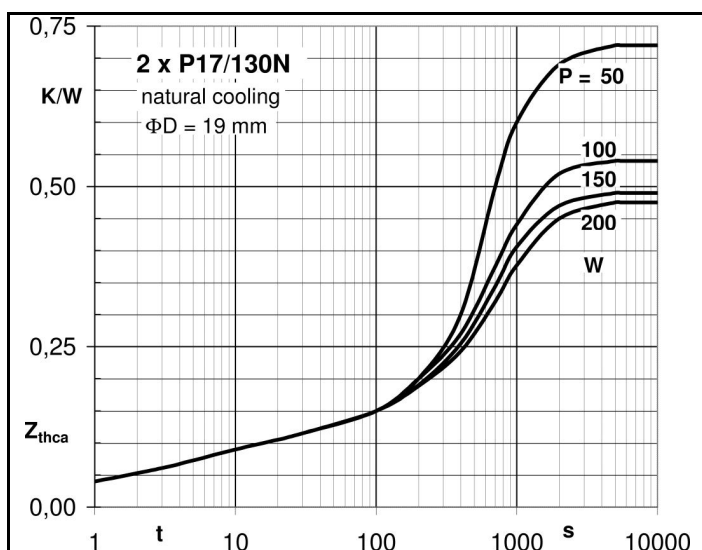


Fig.9a Transient thermal impedance vs. time

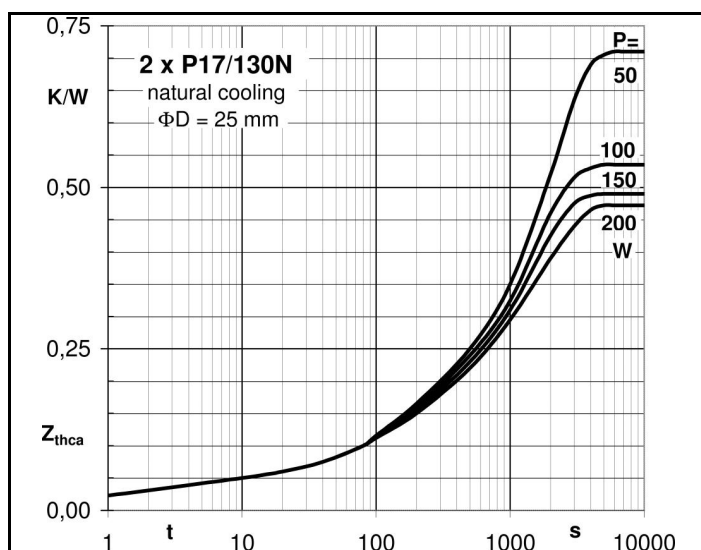


Fig.9b Transient thermal impedance vs. time

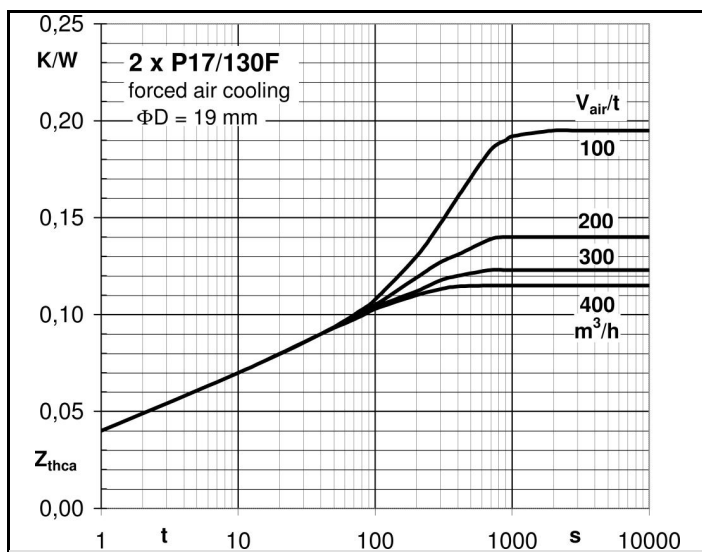


Fig.11a Transient thermal impedance vs.time

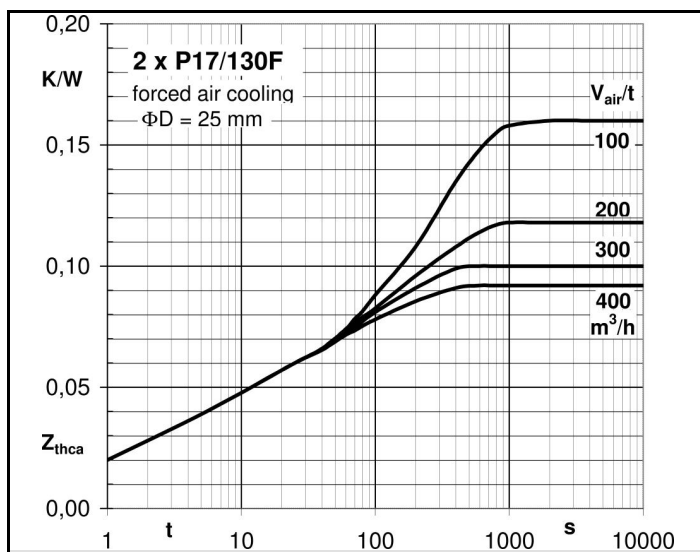


Fig.11b Transient thermal impedance vs.time

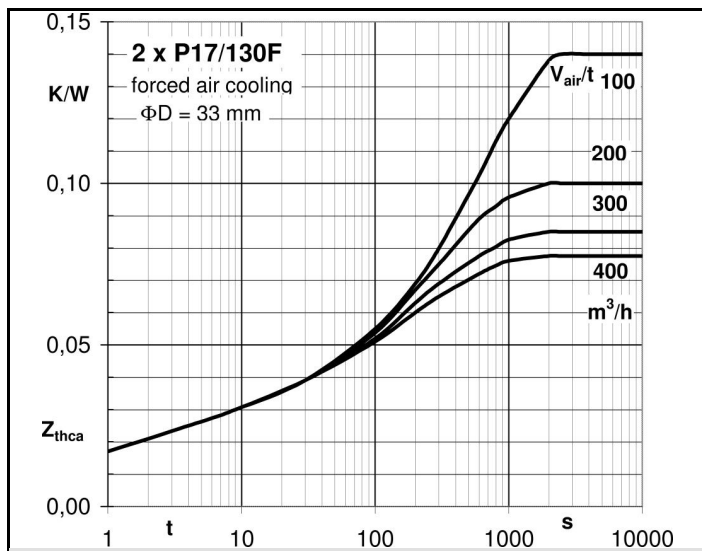


Fig.11c Transient thermal impedance vs.time

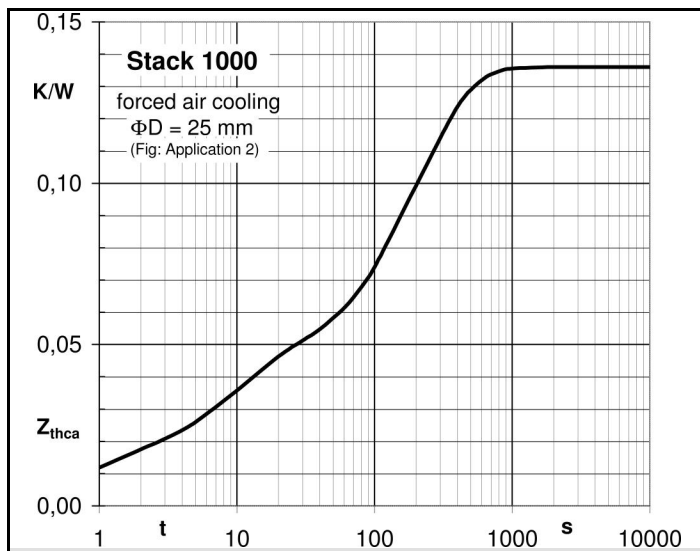


Fig.11d Transient thermal impedance vs.time

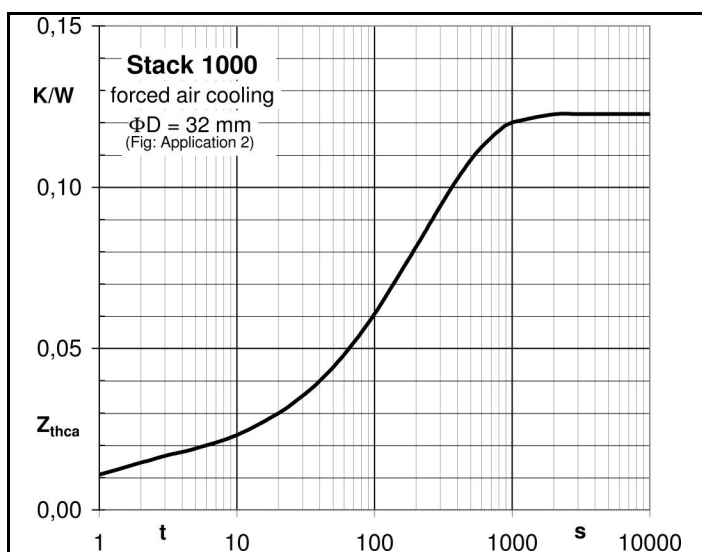


Fig.11e Transient thermal impedance vs.time

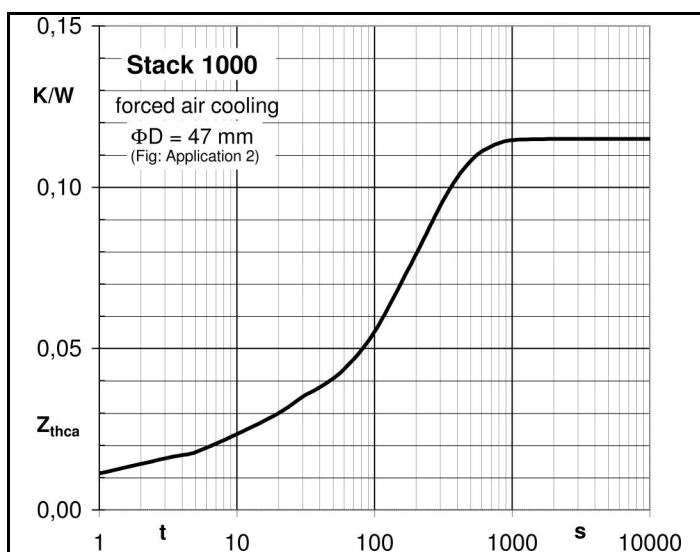
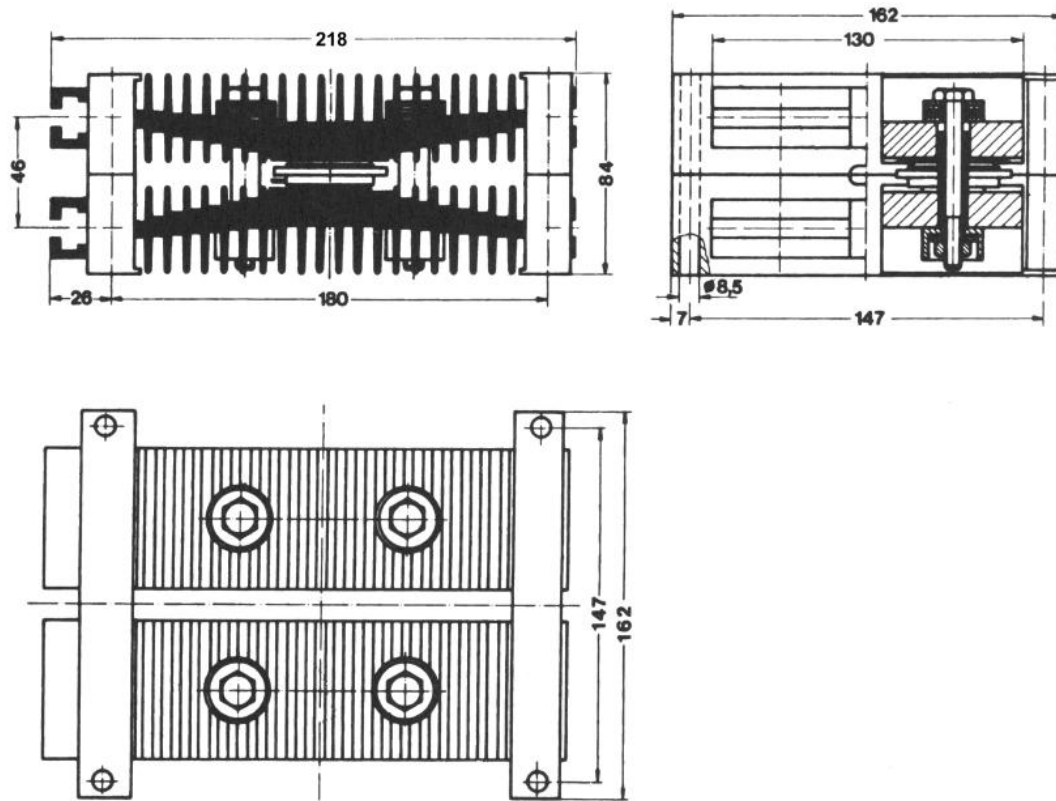


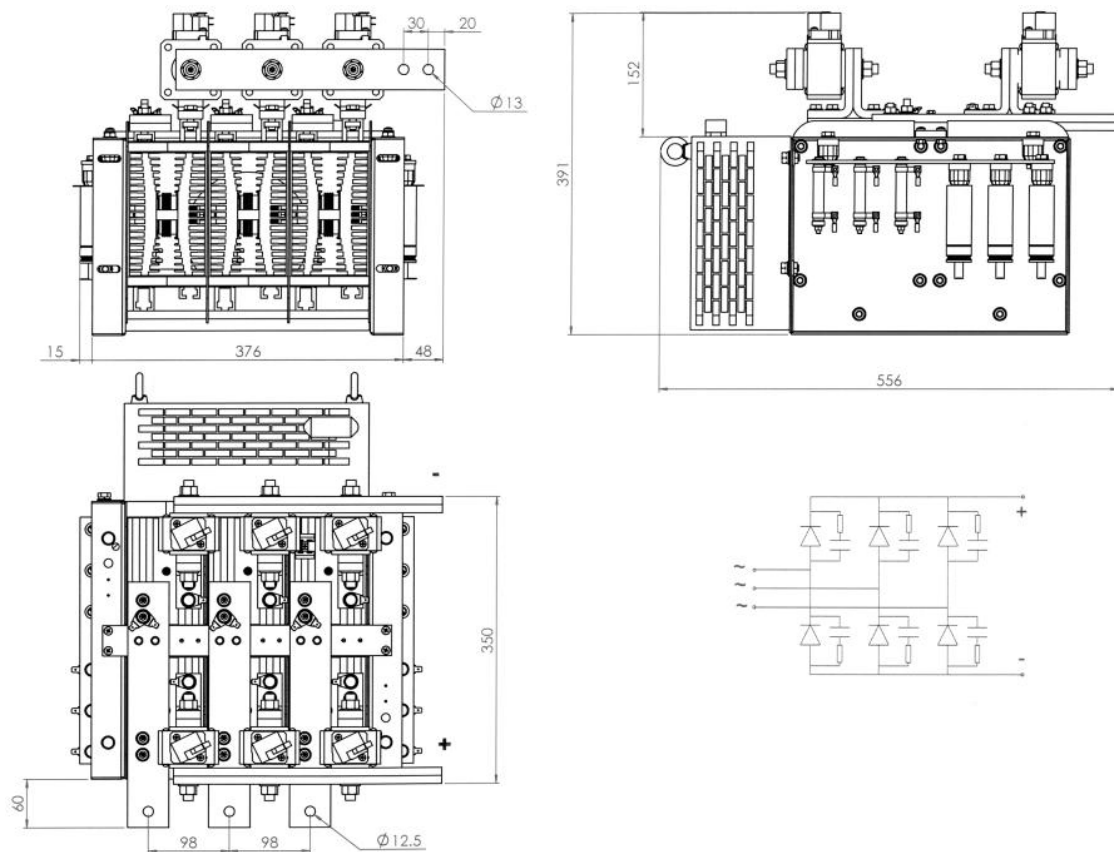
Fig.11f Transient thermal impedance vs.time

Dimensions in mm



1. Setup example of heatsink P 17/130 + 2x P 17/60 with 2 capsules

Dimensions in mm



2. Application example using P17/130 and capsule devices to give a three phase bridge rectifier (Stack 1000)